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PATENT  
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2858  
For : WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY ,  
APPARATUS FOR USE THEREOF  
AND METHODS OF  
FABRICATION THEREOF

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

Supplementing the response filed August 27, 2003 to the Official Action dated May 27, 2003, please amend the above-identified application by removing the page in the aforementioned amendment which contains Claims 31 to 35, and substitute the enclosed page therefor.

Applicants' attorney noted in reviewing this amendment after it was dispatched to the Patent Office, that Claim 32 was erroneously still dependent upon Claim 3 which has been cancelled. Accordingly, a revised Claim 32 is included in the enclosed page. Claim 32 as rewritten now depends upon Claim 1.



In view of the arguments and modifications to the claims, allowance of this case is warranted. Such favorable action is respectfully solicited.

Respectfully Submitted,

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I hereby certify that this paper is being deposited on the date indicated below with the U.S. Postal Service as First Class Mail addressed to Commissioner of Patents & Trademarks, Post Office Box 1450, Alexandria, VA 22313

Signature: *Thomas A. Beck*  
Name: Thomas A. Beck

Date: September 4, 2003

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